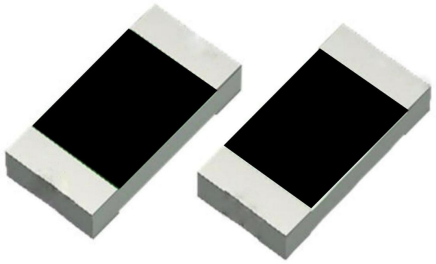
Z06F0.5TH

0603 Fast Acting SMD Fuses

Datasheet-production date

Descriptions

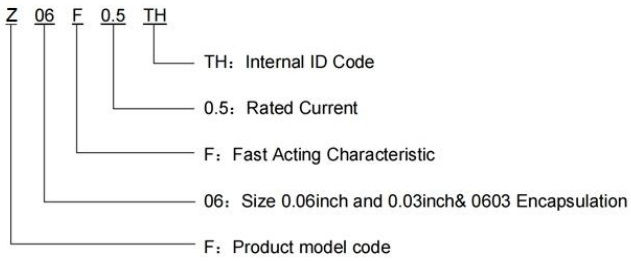
Z06F0.5TH is the fuses set the industry standard for performance,reliability and quality. The ultra small(0603 size) thin-film design provides superior inrush withstand characteristics(I^2t) and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.



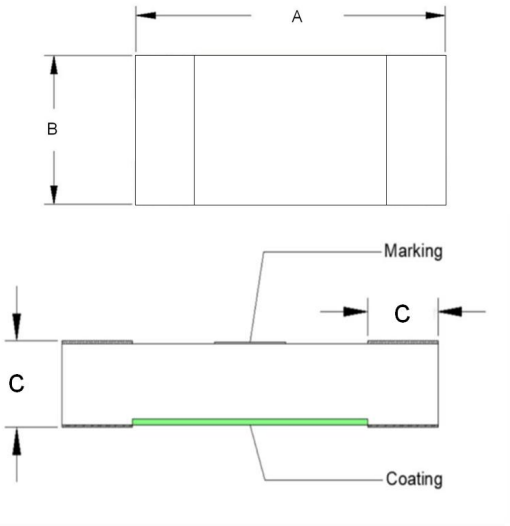
Features

- Compatible with reflow and wave solder
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material

Part Number Coding System



Dimensions



Ref.	Millimeters	
	Min	Max
A	1.40	1.80
B	0.60	1.00
C	0.17	0.47

Specifications

Part No.	Rated Voltage DC(V)	Rated Current(A)	Breaking Capacity[1]	Typical Cold Resistance[2] (mΩ)	Typical Voltage Drop (mV)	Typical Pre- Arcing I^2t $(A^2Sec)^3$
Z06F0.5TH	32	0.5	50A@32V DC	200	152	0.0075

Note:

1.DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)

2.DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25℃

3.Typical Pre-arcing I^2t are measured at 10In Current

Typical Characteristics Curves

Figure 1. Temperature-Current Curve

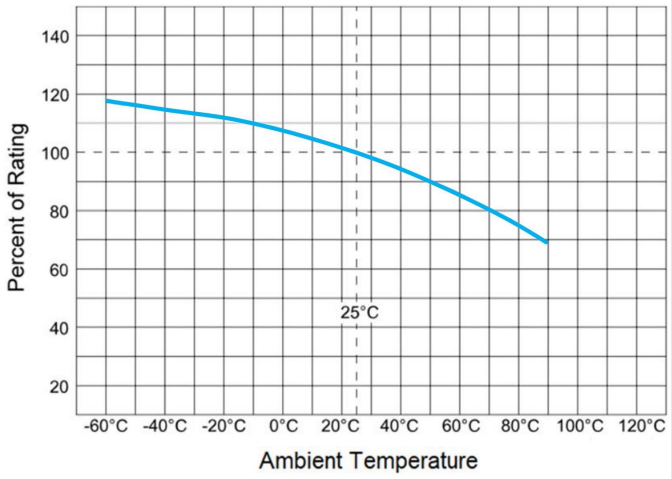
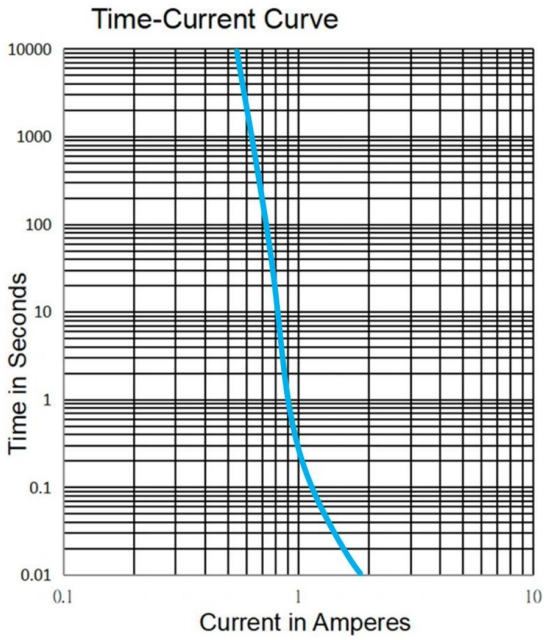
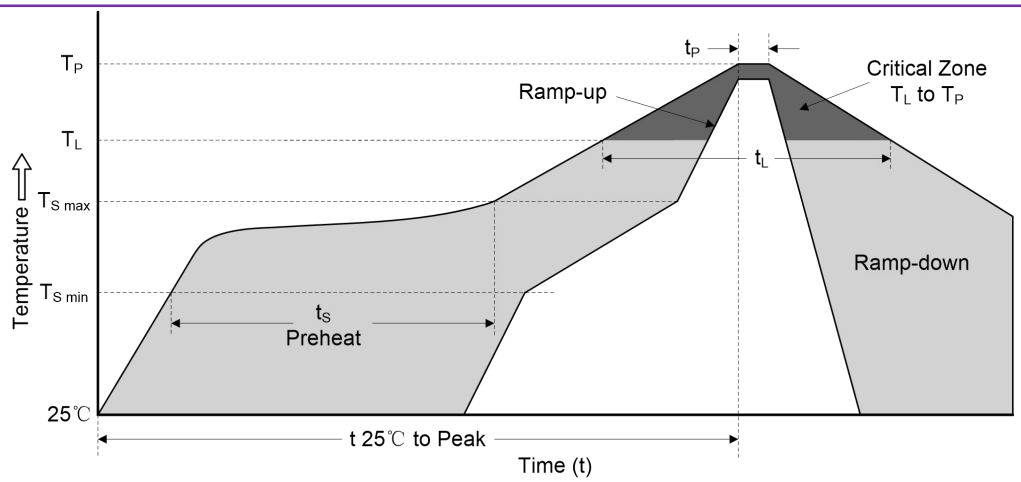


Figure 2. Time-Current Curve



Reflow Soldering Parameters



Reflow Condition		Lead-free Assembly
Pre heat	-Temperature Min ($T_{S\ min}$)	150℃
	-Temperature Max ($T_{S\ max}$)	200℃
	-Time (min to max) (t_S)	60-180 seconds
Average ramp-up rate (T_L to T_P)		3℃/second max.
$T_{S\ max}$ to T_L -Ramp-up Rate		3℃/second max.
Reflow	-Temperature (T_L) (Liquidus)	217℃
	-Time (min to max) (t_S)	60-150 seconds
Peak Temperature (T_P)		260(+0/-5)℃
Time within 5℃ of actual Peak Temperature (t_P)		10-30 seconds
Ramp-down Rate		6℃/second max.
Time 25℃ to Peak Temperature(T_p)		8 minutes max.
Do not exceed		260℃

Package

Part number	QTY/Reel	Reel Size
Z06F0.5TH	5000PCS	Tape and Reel